DATASHEET 规格书

SISD0900ED170i23

ED-Type phase leg IGBT module
ED 封装半桥 IGBT 模块

V_{CE} = 1700 V
I_C = 2 x 900 A

- *i23* ultra-low loss micropattern Trench IGBT chip-set
  i23 超低损耗微沟槽栅 IGBT 芯片组
- Baseplate isolation with reinforced Al_2O_3 ceramic
  加强 Al_2O_3 绝缘陶瓷基板
- Cu baseplate for low thermal resistance
  低热阻铜底板
- Industry standard package with reduced internal impedance
- 行业标准封装，低内部阻抗

Maximum ratings[1] 最大额定值 [1]

PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件	MIN 最小值	MAX 最大值	UNIT 单位
Collector-emitter voltage 集电极-发射极电压	V_{CES}	V_{GE} = 0 V, T_{vj} = 25 °C		1700	V
DC collector current 集电极直流电流	I_C	T_C = 95 °C, T_{vj} = 175 °C		900	A
Peak collector current 集电极峰值电流	I_{CM}	t_p = 1 ms		1800	A
Gate-emitter voltage 栅极-发射极驱动电压	V_{GES}		-20	20	V
Total power dissipation 最大功率损耗	P_{tot}	T_C = 25 °C, T_{vj} = 175 °C, per switch		3660	W
DC forward current 二极管直流正向电流	I_F			900	A
Peak forward current 二极管最大脉冲正向电流	I_{FRM}	t_p = 1 ms		1800	A
Surge current 二极管最大浪涌电流	I_{FSM} I^2t	V_R = 0 V, T_{vj} = 150 °C, t_p = 10 ms, half-sinewave		2800 40000	A A^2s
Isolation voltage 绝缘电压	V_{isol}	1 min, f = 50 Hz		3400	V
Junction operating temperature 运行结温	$T_{vj(op)}$		-40	175	°C
Case temperature 壳温	T_C		-40	125[2]	°C
Storage temperature 存储温度	T_{stg}		-40	125	°C
Mounting torques 紧固力矩[3]	M_S	Base-heatsink, M5 screws	3	6	Nm
	M_{t1}	Main terminals, M6 screws	3	6	Nm

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[1] Maximum rated values indicate limits beyond which damage to the device may occur per IEC 60747; 根据标准 IEC 60747 要求，最大额定值表示超过该限值可能会对器件造成损坏
[2] For UL1557 compliance T_{Cmax} must be limited to 125°C
[3] For details, please refer to the mounting instructions. 详细信息，请参考安装说明书

IGBT[4]

PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件		MIN 最小值	TYP 典型	MAX 最大值	UNIT 单位
Collector(-emitter) breakdown voltage 集电极-发射极击穿电压	$V_{(BR)CES}$	V_{GE} = 0 V, I_C = 1 mA, T_{vj} = 25°C		1700			V
Collector-emitter saturation voltage [5] **集电极-发射极饱和电压**	V_{CEsat}	I_c = 900 A, V_{GE} = 15 V	T_{vj} = 25 °C		1.75	2.1	V
			T_{vj} = 125 °C		2.0		V
			T_{vj} = 175 °C		2.15		V
Collector cut-off current **集电极截止电流**	I_{CES}	V_{CE} = 1700 V, V_{GE} = 0 V	T_{vj} = 25 °C			1	mA
			T_{vj} = 125 °C		5		mA
			T_{vj} = 175 °C		45		mA
Gate leakage current 栅极漏电流	I_{GES}	V_{CE} = 0 V, V_{GE} = ±20 V		-0.5		0.5	µA
Gate-emitter threshold voltage 栅极-发射极阈值电压	$V_{GE(th)}$	I_C = 30 mA, V_{CE} = V_{GE}, T_{vj} = 25°C		5.0	6.0	7.0	V
Gate charge 栅极电荷	Q_G	I_C = 900 A, V_{CE} = 900 V, V_{GE} = -15 V .. 15 V			7.8		µC
Input capacitance 输入电容	C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V, f = 100 kHz, T_{vj} = 25 °C			113		nF
Output capacitance 输出电容	C_{oes}				2.89		nF
Reverse tansfer capacitance 反向传输电容	C_{res}				0.72		nF
Internal gate resistor 栅极内阻	R_{Gint}	Per switch, f = 1 MHz, V_{GE} = 0V, CE short			0.33		Ω
Turn-on delay time 开通延迟时间	$t_{d(on)}$	V_{CC} = 900 V, I_C = 900 A, R_G = 0.5 Ω, V_{GE} = ± 15 V, L_s = 35 nH, inductive load	T_{vj} = 25 °C		170		ns
			T_{vj} = 125 °C		195		ns
			T_{vj} = 175 °C		215		ns
Rise time **上升时间**	t_r		T_{vj} = 25 °C		75		ns
			T_{vj} = 125 °C		85		ns
			T_{vj} = 175 °C		91		ns
Turn-off delay time 关断延迟时间	$t_{d(off)}$	V_{CC} = 900 V, I_C = 900 A, R_G = 1.5 Ω, V_{GE} = ± 15 V, L_s = 35 nH, inductive load	T_{vj} = 25 °C		512		ns
			T_{vj} = 125 °C		609		ns
			T_{vj} = 175 °C		654		ns
Fall time **下降时间**	t_f		T_{vj} = 25 °C		370		ns
			T_{vj} = 125 °C		527		ns
			T_{vj} = 175 °C		601		ns
Turn-on switching energy **开通损耗**	E_{on}	V_{CC} = 900 V, I_C = 900 A, R_G = 0.5 Ω, V_{GE} = ± 15 V, L_s = 35 nH, inductive load	T_{vj} = 25 °C		147		mJ
			T_{vj} = 125 °C		232		mJ
			T_{vj} = 175 °C		290		mJ
Turn-off switching energy **关断损耗**	E_{off}	V_{CC} = 900 V, I_C = 900 A, R_G = 1.5 Ω, V_{GE} = ± 15 V, L_s = 35 nH, inductive load	T_{vj} = 25 °C		187		mJ
			T_{vj} = 125 °C		256		mJ
			T_{vj} = 175 °C		286		mJ
Short circuit current 短路电流	I_{SC}	t_{pcs} ≤ 6 µs, V_{GE} = 15 V, T_{vj} = 175 °C, $R_{G,on}$ = 1.5 Ω, V_{CC} = 1100V, $V_{CEM\ Chip}$ ≤ 1700 V			3500		A

[4] Characteristic values according to IEC 60747-9
[5] Collector-emitter saturation voltage is given at chip-level 集电极-发射极饱和电压

Diode[6]

PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件		MIN 最小值	TYP 典型	MAX 最大值	UNIT 单位
Forward voltage[7] 正向压降	V_F	I_F = 900 A	T_{vj} = 25 °C		2.0	2.3	V
			T_{vj} = 125 °C		2.25		V
			T_{vj} = 175 °C		2.2		V
Peak reverse recovery current 反向恢复电流峰值	I_{RM}	V_R = 900 V, I_F = 900 A, dI_F/dt = 9.9 kA/µs (175 °C), R_G =0.5 Ω, V_{GE} = ± 15 V, L_s = 35 nH, inductive load	T_{vj} = 25 °C		936		A
			T_{vj} = 125 °C		1040		A
			T_{vj} = 175 °C		1080		A
Recovery charge 恢复电荷	Q_{rr}		T_{vj} = 25 °C		143		µC
			T_{vj} = 125 °C		245		µC
			T_{vj} = 175 °C		307		µC
Reverse recovery time 反向恢复时间	t_{rr}		T_{vj} = 25 °C		631		ns
			T_{vj} = 125 °C		926		ns
			T_{vj} = 175 °C		1132		ns
Reverse recovery energy 反向恢复能量	E_{rec}		T_{vj} = 25 °C		89		mJ
			T_{vj} = 125 °C		144		mJ
			T_{vj} = 175 °C		176		mJ

NTC Thermistor

PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件	MIN 最小值	TYP 典型	MAX 最大值	UNIT 单位
Rated resistance 额定电阻	R_{25}	T_C = 25 °C		5		kΩ
R100	R_{100}	T_C = 100 °C	468		518	Ω
B-value B 值	$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50}(1/T2 - 1/(298.15K))]$		3375		K
B-value B 值	$B_{25/100}$	$R_2 = R_{25} \exp [B_{25/100}(1/T2 - 1/(298.15K))]$		3433		K

[6] Characteristic values according to IEC 60747-2
[7] Forward voltage is given at chip-level 正向压降是芯片两端的电压值。

Package properties 封装特性[8]

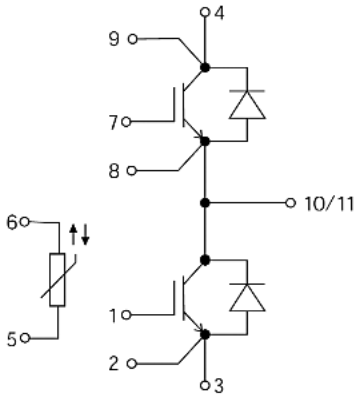
PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件		MIN 最小值	TYP 典型	MAX 最大值	UNIT 单位
IGBT thermal resistance junction to case **IGBT** 结-壳热阻	$R_{th(j-c)IGBT}$	Per switch 每一个开关				0.041	K/W
Diode thermal resistance junction to case 二极管结-壳热阻	$R_{th(j-c)Diode}$					0.069	K/W
IGBT thermal resistance case to heatsink **IGBT** 壳到散热器热阻	$R_{th(c-s)IGBT}$	IGBT per switch IGBT 每一个开关			0.030		K/W
Diode thermal resistance case to heatsink 二极管壳到散热器热阻	$R_{th(c-s)Diode}$	diode per switch 二极管每一个开关			0.036		K/W
Comparative tracking index 相对漏电起痕指数	CTI			200			
Module stray inductance 模块自身杂散电感	$L_{s\ CE}$	Per switch 每一个开关			16		nH
Resistance, terminal chip **端子到芯片之间的阻抗**	$R_{CC'+EE'}$	Per switch 每一个开关	T_{vj} = 25 °C		0.7		mΩ
			T_{vj} = 125 °C		1.0		mΩ
			T_{vj} = 175 °C		1.1		mΩ
Maximum RMS DC-Terminal current 直流端子最大电流（有效值）	$I_{Term\ RMS}$		$T_{Terminal}$ = 90°C		590		A
			$T_{Terminal}$ = 105°C		565		A

Mechanical properties 机械特性

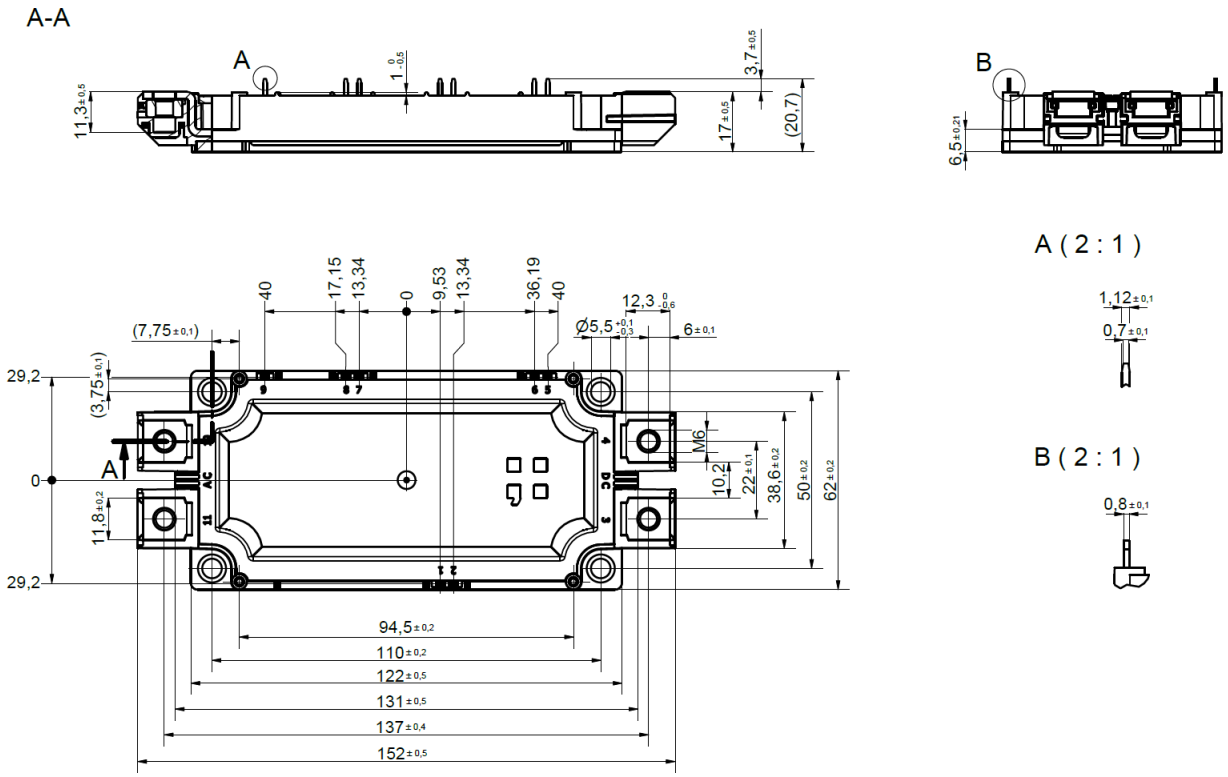
PARAMETER 参数	SYMBOL 符号	CONDITIONS 工作条件		MIN 最小值	TYP 典型	MAX 最大值	UNIT 单位
Dimensions	L x W x H	Typical		152 x 62 x 17			mm^3
Clearance distance in air 电气间隙	d_a	According to IEC 60664-1 and EN 50124-1 参考标准 IEC 60664-1 和 EN 50124-1	Terminal to base: 端子到底板	12.5			mm
			Terminal to terminal: 端子到端子	10			mm
Surface creepage distance 爬电距离	d_s	According to IEC 60664-1 and EN 50124-1 参考标准 IEC 60664-1 和 EN 50124-1	Terminal to base: 端子到底板	15			mm
			Terminal to terminal: 端子到端子	13			mm
Mass 重量	m				350		g

[8] Package and mechanical properties according to IEC 60747-15

Electrical configuration 电气图



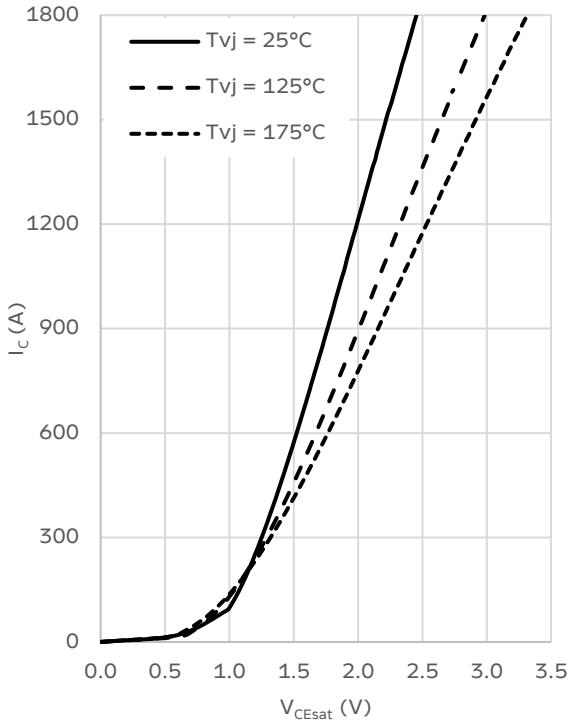
Outline drawing 外形图



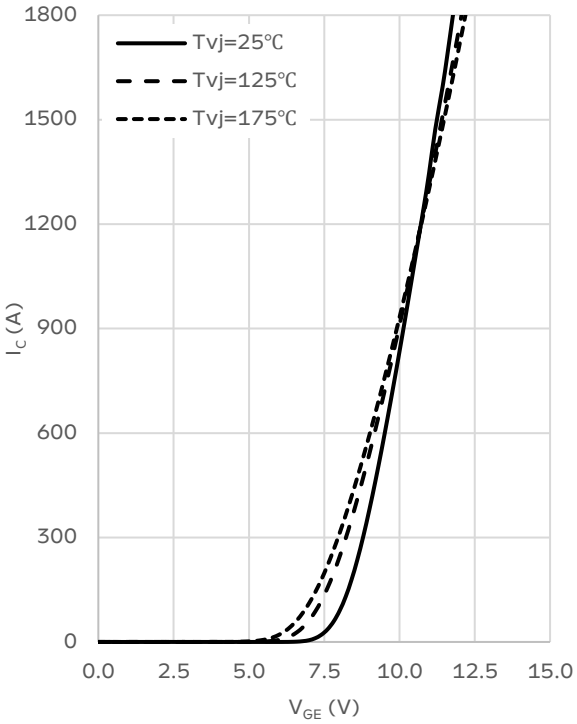
This is an electrostatic sensitive device. 本产品对静电特别敏感.
This product has been designed and qualified for Industrial Level. 本产品的设计符合工业级标准.

Characteristics 特性曲线

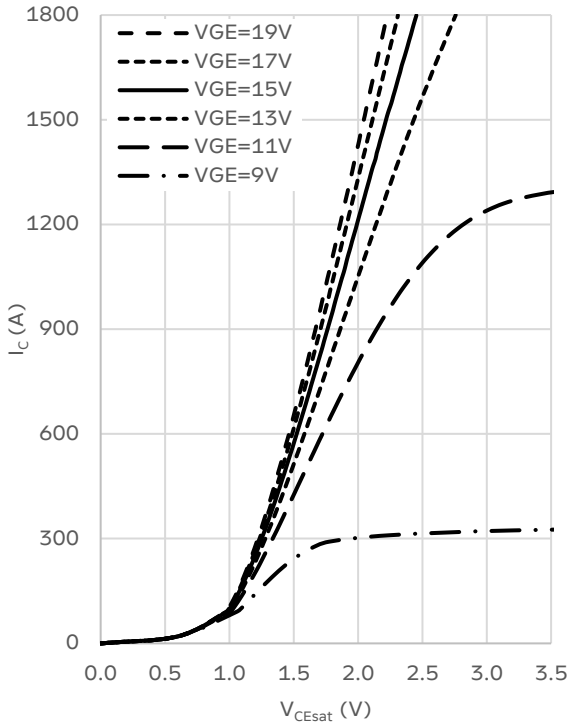
IGBT on-state characteristics (typical)
IGBT 通态特性曲线（典型）
$I_C = f(V_{CE})$
V_{GE} = 15 V



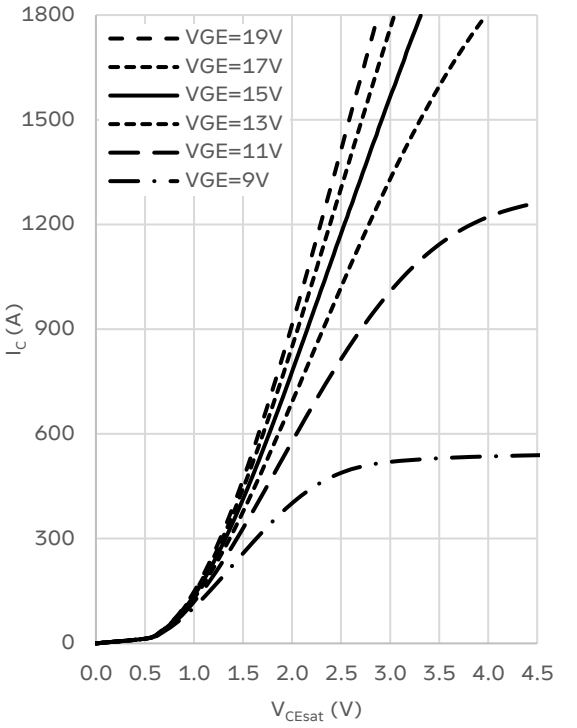
IGBT transfer characteristics (typical)
IGBT 转移特性曲线（典型）
$I_C = f(V_{GE})$
V_{CE} = 20V



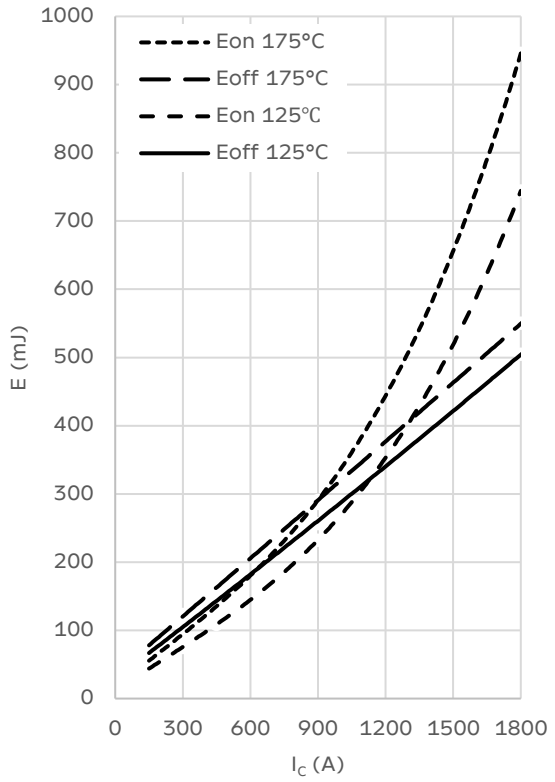
IGBT output characteristics (typical)
IGBT 输出特性曲线（典型）
$I_C = f(V_{CE})$
T_{vj} = 25 °C



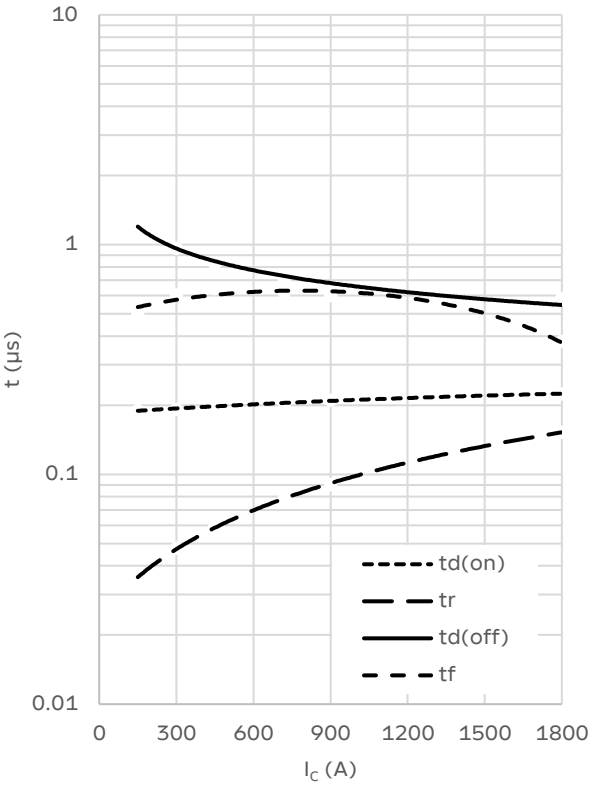
IGBT output characteristics (typical)
IGBT 输出特性曲线（典型）
$I_C = f(V_{CE})$
T_{vj} = 175 °C



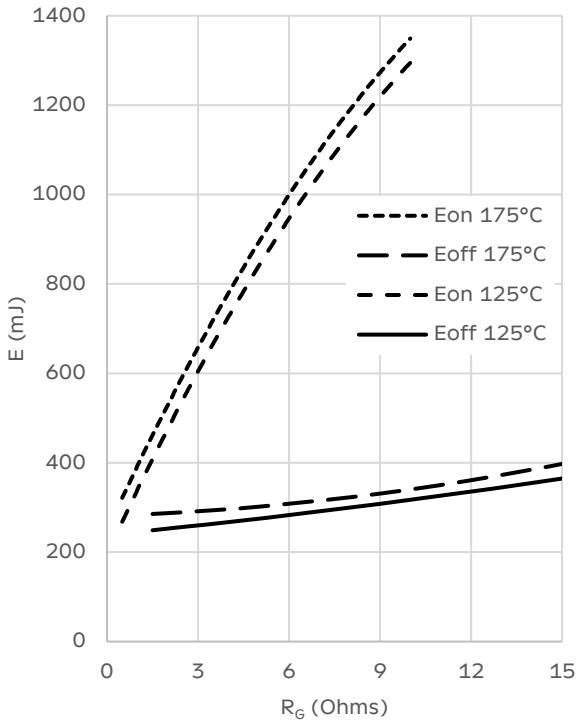
IGBT switching losses (typical)
IGBT 开关损耗曲线（典型）
$E = f(I_{CE})$
V_{CE} = 900 V, R_{Gon} = 0.5 Ω, R_{Goff} = 1.5 Ω, V_{GE} = -15/+15 V



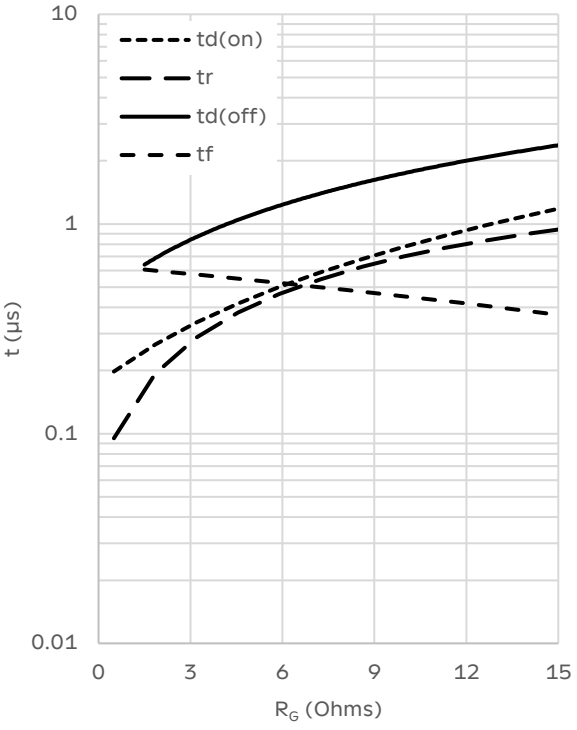
IGBT switching times (typical)
IGBT 开关时间曲线（典型）
$t = f(I_{CE})$, T_{vj} = 175 °C
V_{CE} = 900 V, R_{Gon} = 0.5 Ω, R_{Goff} = 1.5 Ω, V_{GE} =-15/+15 V



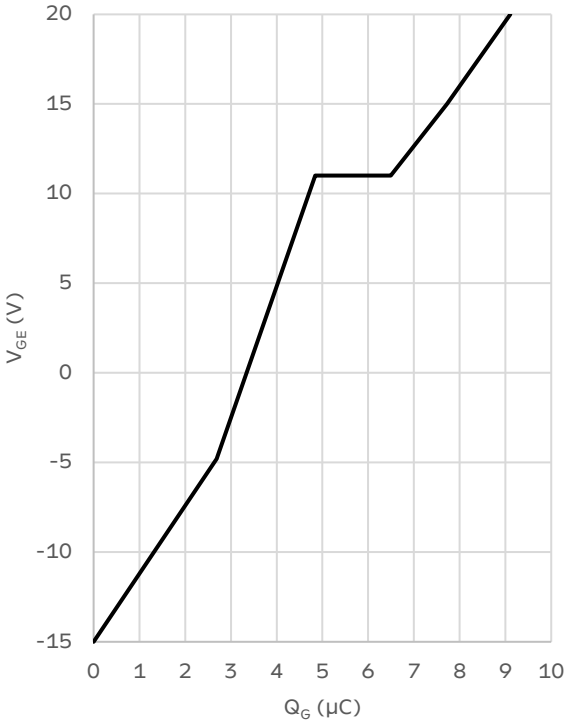
IGBT switching losses (typical)
IGBT 开关损耗曲线（典型）
$E = f(R_G)$
V_{CE} = 900 V, I_C = 900 A, V_{GE} = -15/+15 V



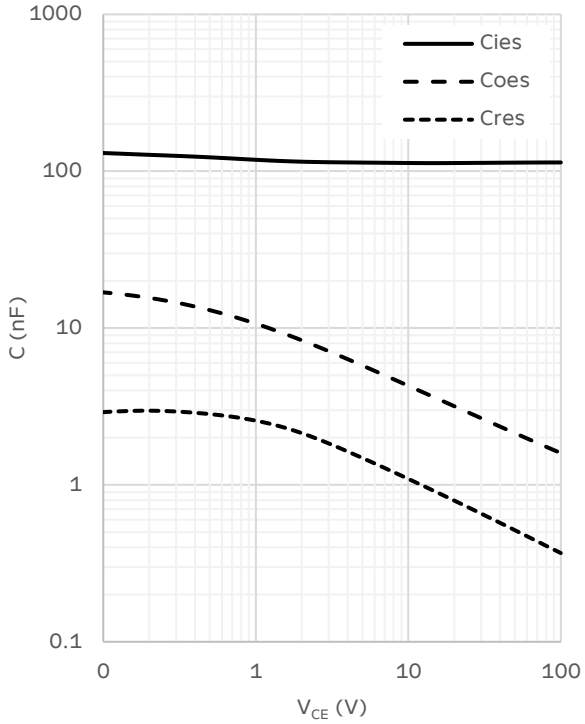
IGBT switching times (typical)
IGBT 开关时间曲线（典型）
$t = f(R_G)$, T_{vj} = 175 °C
V_{CE} = 900 V, I_C = 900 A, V_{GE} = -15/+15 V



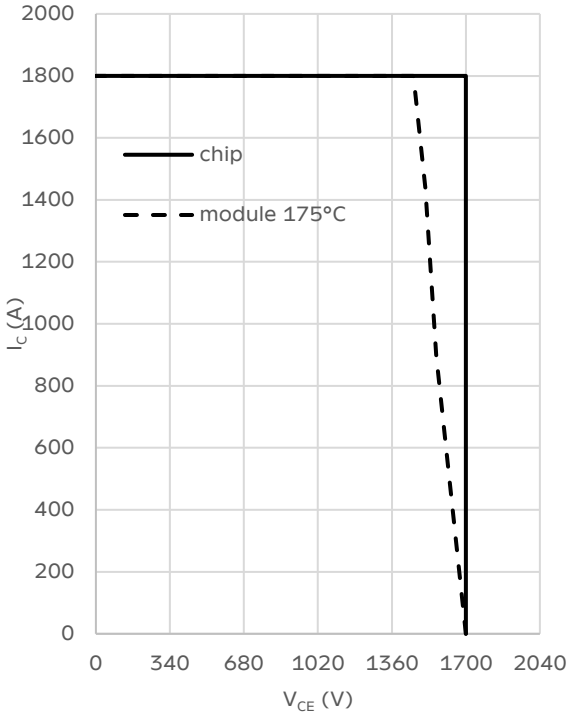
IGBT gate charge (typical)
IGBT 门极电荷（典型）
$V_{GE} = f(Q_G)$, $T_{vj} = 25$ °C
$V_{CE} = 900$ V, $I_C = 900$ A



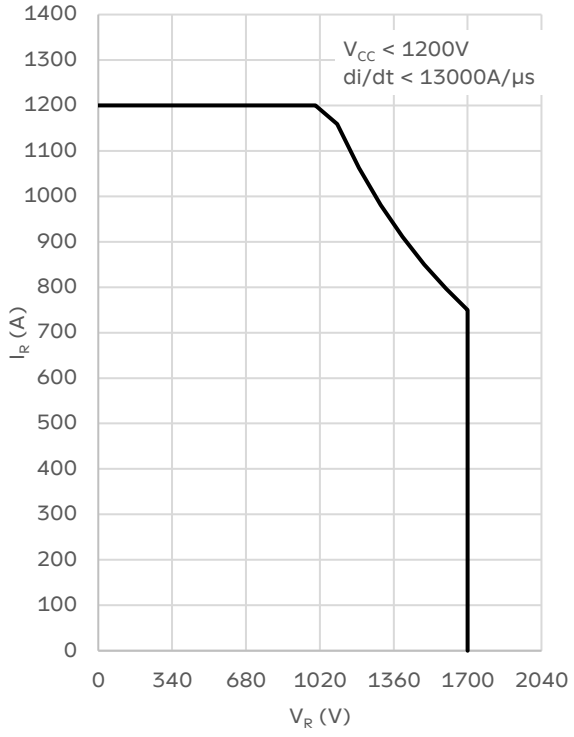
Capacitance characteristics (typical)
电容特性曲线（典型）
$C = f(V_{CE})$, $T_{vj} = 25$ °C
$f = 100$ kHz, $V_{GE} = 0$ V



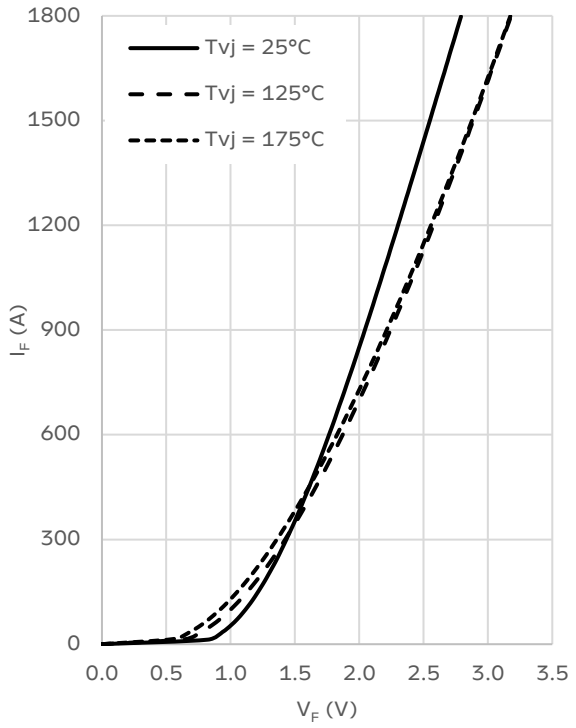
IGBT RBSOA
IGBT 反偏安全工作区域
$I_C = f(V_{CEm})$
$R_{Goff} = 1.5\ \Omega$, $V_{GE} = \pm 15$ V



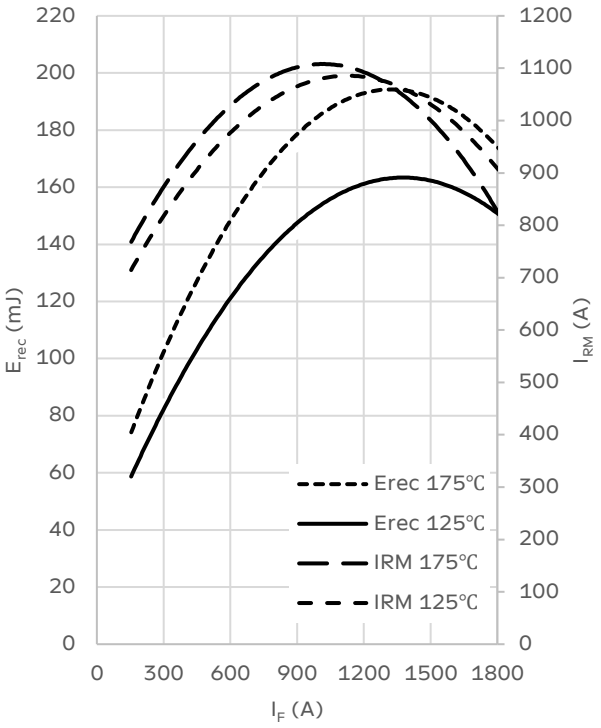
Diode SOA
Diode 反偏安全工作区域
$T_{vj} \leq 175$ °C



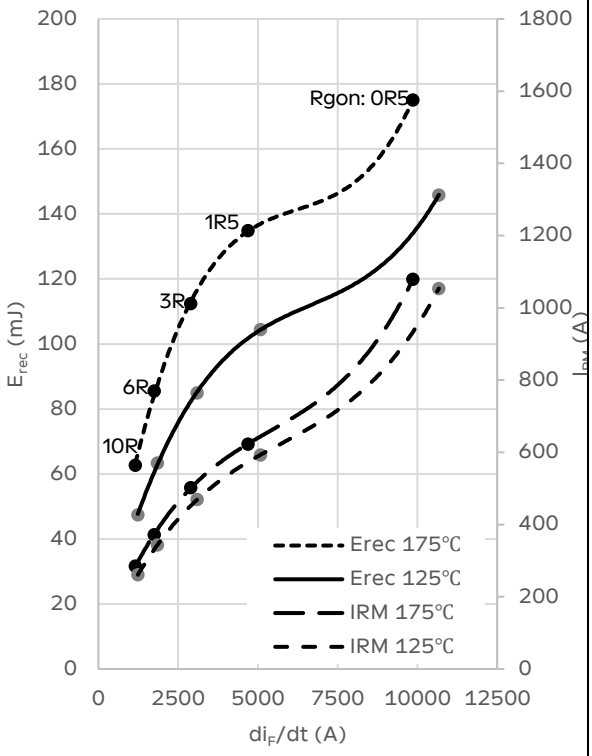
Diode forward characteristic (typical)
二极管正向特性（典型）
$I_F = f(V_F)$



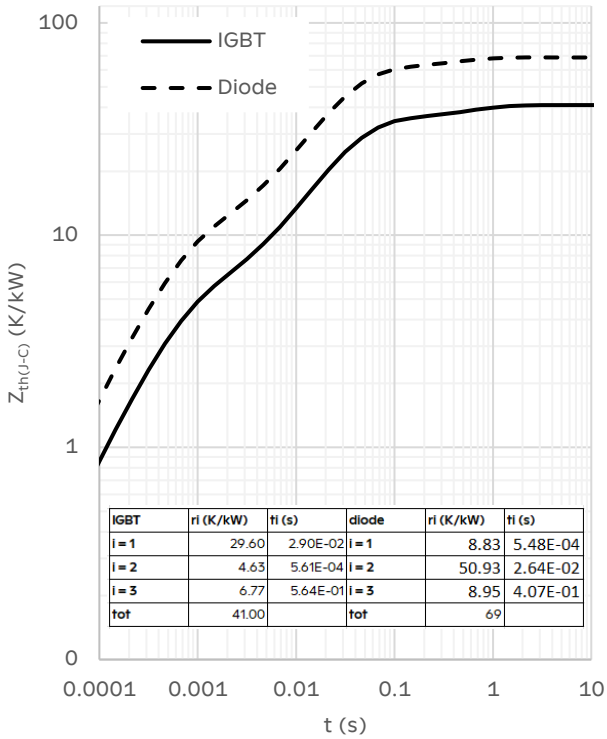
Diode switching characteristics (typical)
二极管开关特性（典型）
$E_{rec} = f(I_F)$, $I_{RM} = f(I_F)$
V_{DC} = 900 V, R_{Gon} = 0.5 Ω (IGBT), V_{GE} =-15/+15 V (IGBT)



Diode switching characteristics (typical)
二极管开关特性（典型）
$E_{rec} = f(di/dt)$, $I_{RM} = f(di/dt)$
V_{DC} = 600 V, I_F = 600 A, V_{GE} =-15/+15 V (IGBT)



Thermal impedance
热阻抗（典型）
$Z_{th(j-c)} = f(t)$



IGBT	ri (K/kW)	ti (s)	diode	ri (K/kW)	ti (s)
i = 1	29.60	2.90E-02	i = 1	8.83	5.48E-04
i = 2	4.63	5.61E-04	i = 2	50.93	2.64E-02
i = 3	6.77	5.64E-01	i = 3	8.95	4.07E-01
tot	41.00		tot	69	

Revision History 修订历史

Release 发布	Version 版本	Description 描述
2026-07-23	V5.0	Final Datasheet 最终数据表